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August 2010

FDS86242

N-Channel PowerTrench[®] MOSFET 150 V, 4.1 A, 67 m Ω

Features

- Max $r_{DS(on)}$ = 67 m Ω at V_{GS} = 10 V, I_D = 4.1 A
- Max $r_{DS(on)}$ = 98 m Ω at V_{GS} = 6 V, I_D = 3.3 A
- High performance trench technology for extremely low r_{DS(on)}
- High power and current handling capability in a widely used surface mount package
- 100% UIL Tested
- RoHS Compliant

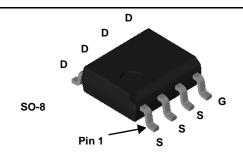


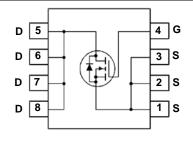
General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been optimized for $r_{DS(on)}$, switching performance and ruggedness.

Applications

- DC/DC converters and Off-Line UPS
- Distributed Power Architectures and VRMs
- Primary Switch for 24V and 48V Systems
- High Voltage Synchronous Rectifier





MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Paran	neter		Ratings	Units
V _{DS}	Drain to Source Voltage			150	V
V_{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous			4.1	А
ID	-Pulsed			20	7
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	40	mJ
В	Power Dissipation	T _C = 25 °C	(Note 1)	5.0	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	2.5	vv
T _J , T _{STG}	Operating and Storage Junction Temper	rature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	25	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS86242	FDS86242	SO-8	13 "	12 mm	2500 units

Electrical Characteristics T_J = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperatur Coefficient	I_D = 250 μ A, referenced to 25 °C		104		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 120 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2	3.5	4	V
$\Delta V_{GS(th)}$ ΔT_J	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-10		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 4.1 \text{ A}$		56.3	67	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 6 \text{ V}, I_D = 3.3 \text{ A}$		73.8	98	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 4.1 \text{ A}, T_J = 125 \text{ °C}$		107	126	
9 _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 4.1 \text{ A}$		11		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 75 V V 0 V	570	760	pF
Coss	Output Capacitance	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1MHz	64	85	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11VII 12	2.9	5	pF
R _a	Gate Resistance		0.5		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		7.9	16	ns
t _r	Rise Time	V _{DD} = 75 V, I _D = 4.1 A,	1.5	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	13	23	ns
t _f	Fall Time		2.8	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V _{GS} = 0 V to 10 V	8.9	13	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to 5 V}$ $V_{DD} = 75 \text{ V},$	4.9	7	nC
Q_{gs}	Gate to Source Charge	I _D = 4.1 A	3.0		nC
Q_{gd}	Gate to Drain "Miller" Charge		2.0		nC

Drain-Source Diode Characteristics

V	Veb 1200LC6 to Digit Diode Forward voltage 1	$V_{GS} = 0 \text{ V}, I_S = 4.1 \text{ A}$	(Note 2)	0.81	1.3	\/
V SD		$V_{GS} = 0 \text{ V}, I_{S} = 2 \text{ A}$	(Note 2)	0.77	1.2	V
t _{rr}	Reverse Recovery Time	L = 4.1 A di/dt = 100 A/va		61	98	ns
Q _{rr}	Reverse Recovery Charge	I _F = 4.1 A, di/dt = 100 A/μs		71	114	nC

^{1.} $R_{\theta,JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta,JC}$ is guaranteed by design while $R_{\theta,CA}$ is determined by the user's board design.



a) 50 °C/W when mounted on a 1 in² pad of 2 oz copper.



b) 125 °C/W when mounted on a minimum pad.

^{2.} Pulse Test: Pulse Width < 300 $\mu s,$ Duty cycle < 2.0%. 3. Starting T $_J$ = 25 °C, $\,$ L = 1 mH, I $_{AS}$ = $\,$ 9 A, V $_{DD}$ = 135 V, V $_{GS}$ = 10 V.

Typical Characteristics T_J = 25 °C unless otherwise noted

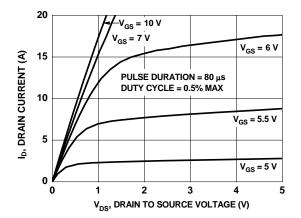


Figure 1. On-Region Characteristics

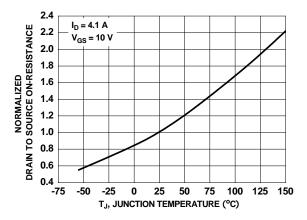


Figure 3. Normalized On-Resistance vs Junction Temperature

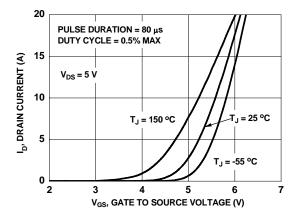


Figure 5. Transfer Characteristics

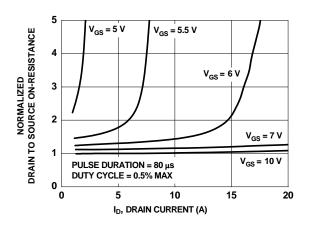


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

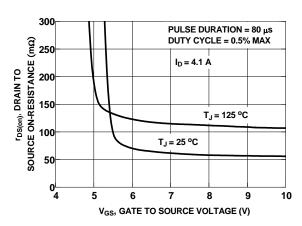


Figure 4. On-Resistance vs Gate to Source Voltage

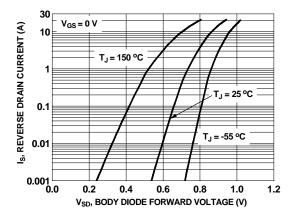


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

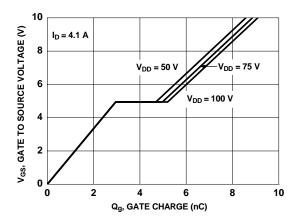


Figure 7. Gate Charge Characteristics

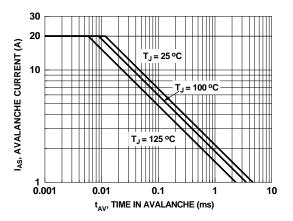


Figure 9. Unclamped Inductive Switching Capability

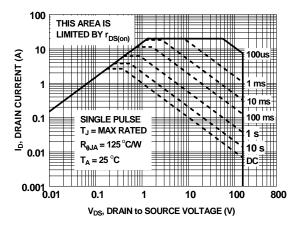


Figure 11. Forward Bias Safe Operating Area

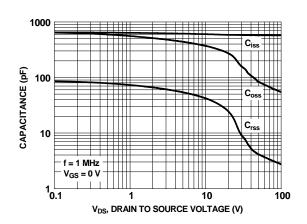


Figure 8. Capacitance vs Drain to Source Voltage

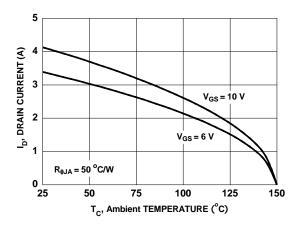


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

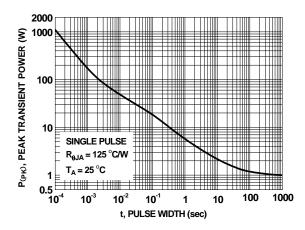


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted

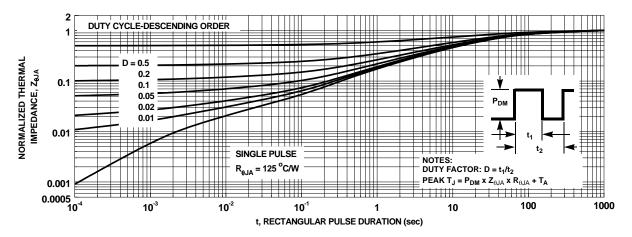


Figure 13. Junction-to-Ambient Transient Thermal Response Curve





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